

PCN# : P235A
Issue Date : Apr. 09, 2012

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples. Alternatively, you may send an email request for data, samples or other information to PCNSupport@fairchildsemi.com.

Implementation of change:

Expected First Shipment Date for Changed Product : Jul. 08, 2012

Expected First Date Code of Changed Product :1245

Last Date for Shipment of Unchanged Product : Jul. 08, 2012

Description of Change (From) :
The 150mm wafer BCH4B and BCH5 Maine fabrication processes

Description of Change (To) :
The 200mm wafer BCH4B and BCH5 Maine fabrication processes

Reason for Change:
To continue to increase Fairchild's manufacturing capacity to support our customers' product growth demands.

Affected Product(s):

FAN1852MX_SN00164	FAN4146ESX	FAN4147SX
FAN5000AMX	RA9100_32	RA9117
RV4141AMT	RV4141AN	RV4145AMT
RV4145AN		

Qualification Plan	Device	Package	Process	No. of Lots
Q20110036	RV4141AM	NMSON008	BCH4B	2

Test Description:	Condition:	Standard :	Duration:	Results:
Bond Pull		JESD22-C100		0/10
Bond Shear		AEC-Q100-001		0/5
Charged Device Model ESD	1.5kV	JESD22-A115		0/3
Dynamic Operation Life	125C,	JESD22-A108	1000 hrs	0/144
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/144
Highly Accelerated Stress Test	130C, 85%RH,	JESD22-A110	264 hrs	5/90
Human Body Model ESD	2.0kV	JESD22-A114		0/3
Latch Up	18v, +300mA, -200mA	JESD78		0/6
MSL1 Preconditioning		JESD22-A113		0/410
Temperature Cycling	-65C, 150C	JESD22-A104	500 Cycles	12/160
Unbiased HAST	110C, 85%RH	JESD22-A118	264 hrs	0/90

Qualification Plan	Device	Package	Process	No. of Lots
Q20110036	FAN1852MX	NMSON008	BCH4B	1

Test Description:	Condition:	Standard :	Duration:	Results:
Bond Pull		JESD22-C100		0/5
Bond Shear		AEC-Q100-001		0/5
Charged Device Model ESD	2.0kV	JESD22-A115		0/3
Dynamic Operation Life	125C,	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Highly Accelerated Stress Test	130C, 85%RH,	JESD22-A110	264 hrs	0/45
Human Body Model ESD	5.0kV	JESD22-A114		0/3
MSL1 Preconditioning		JESD22-A113		0/211
Latch Up	20v, +/-300mA	JESD78		0/6
Temperature Cycling	-65C, 150C	JESD22-A104	500 Cycles	0/77
Unbiased HAST	110C, 85%RH	JESD22-A118	264 hrs	0/45

Qualification Plan	Device	Package	Process	No. of Lots
Q20110036	FAN4146SX	TTK23006	BCH5	1

Test Description:	Condition:	Standard :	Duration:	Results:
Bond Pull		JESD22-C100		0/5
Bond Shear		AEC-Q100-001		0/5
Charged Device Model ESD	2.0kV	JESD22-A115		0/3
Dynamic Operation Life	125C,	JESD22-A108	1000 hrs	0/77
High Temperature Storage Life	150C	JESD22-A103	1000 hrs	0/77
Highly Accelerated Stress Test	130C, 85%RH,	JESD22-A110	264 hrs	0/45
Human Body Model ESD	2.0kV	JESD22-A114		0/3
Latch Up	20v, +/-300mA	JESD78		0/6
MSL1 Preconditioning		JESD22-A113		0/211
Temperature Cycling	-65C, 150C	JESD22-A104	500 Cycles	0/77
Unbiased HAST	110C, 85%RH	JESD22-A118	264 hrs	0/45